

Invisipin[®] Test Sockets

Interposers & test sockets with
Invisipin[®] contactor technology

Invisipin[®] interposers and test sockets are based on patented Invisipin[®] technology that enables an easily removable and replaceable transparent electrical connection between devices and test equipment. Utilizing a pad defined, isotropic conductive elastomer, Invisipin's[®] extremely short signal path, low resistance, as well as ultra-low inductance and capacitance deliver the clearest possible picture of how your device is performing. Invisipin[®] technology is quite effective in high frequency applications.

SPECIFICATIONS

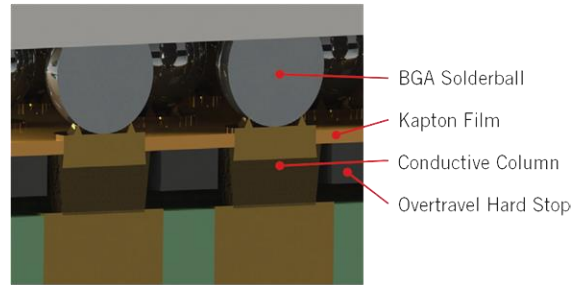
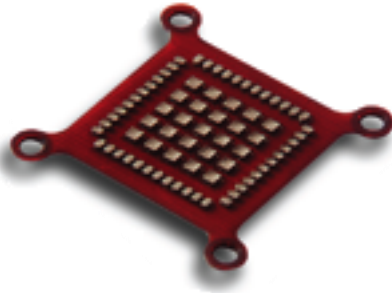
Contact Pitch Sizes	0.3mm, 0.4mm, 0.5mm, 0.65mm, 0.8mm, 1.0mm (custom pitches available)
Bandwidth	< -1 dB through 40 GHz
Current Carrying Capabilities	1 - 4 Amps/pin
Contact DC Resistance	10 - 30 mΩ
Environmental	-40°C to +150°C
Self Inductance	0.03 nH – 0.06nH
Mutual Inductance	0.010 nH – 0.015nH
Typical Contact Force	12 – 35 grams/pin
Contact Compliance	75 μm – 200 μm

Contact R&D Interconnect Solutions for a quote on your test configuration.

OUTSTANDING ELECTRICAL CHARACTERISTICS

R&D Interconnect Solutions (RDIS) test sockets are optimized for use with our patented Invisipin[®] interconnects. These test sockets offer low contact resistance and have been used at clock speeds beyond 40GHz.

Invisipin® Interposer



BEST MATERIALS FOR EXCELLENT DURABILITY

RDIS test sockets typically have a base of Torlon, which is an outstanding insulator with excellent thermal properties. Invisipin® interconnects are more durable than other elastomer-based products. Built on a Kapton foundation, our interconnects use gold/nickel-plated copper pads to contact package leads.

FAST REPLACEMENT & AFFORDABLE

An RDIS Invisipin® interface can be replaced in minutes, saving considerable time and expense when compared to a spring probe solution. RDIS test sockets and interposers are a cost effective option for demanding applications resulting in a lower overall cost of ownership.

AVAILABLE FOR MOST SURFACE MOUNT PACKAGES

RDIS provides a variety of designs for virtually all surface-mount packages (BGA, QFN, QFP, etc.), with pitches down to 0.30 mm. Invisipin® products allow very tight component placement and custom keep-outs. Board to DUT Invisipin® interconnects also penetrate oxidation better than other elastomer-based products by using micro-formed metal contacts. Let us provide a quote for your device package/test socket.

LATEST DESIGNS

RDIS sockets use the most advanced technology to meet your specific needs. Compression blocks feature 3 axes of movement for precise, even pressure. Heat sinks, cooling fans and access for test probes can be incorporated to accommodate your most challenging design requirements.

MAXIMIZE TEST BOARD LIFE

Unlike most interconnect options, our Invisipin® solutions use a flex material that allows for near-zero abrasive contact with your test board. An RDIS Invisipin® solution will prolong performance, extend valuable cycle life of your test board, and reduce expense.

R&D INTERCONNECT SOLUTIONS

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